



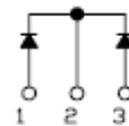
## STF30150C(R) SCHOTTKY RECTIFIER

### Applications:

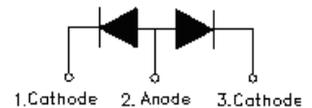
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

### Features:

- 150 °C T<sub>J</sub> operation
- Center tap configuration
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

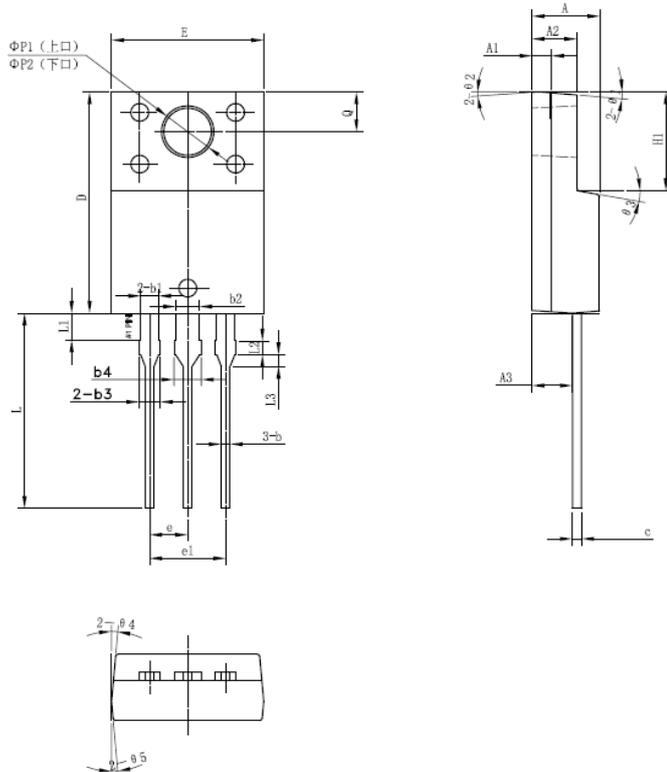


**STF30150C**



**STF30150CR**

### Mechanical Dimensions: In mm

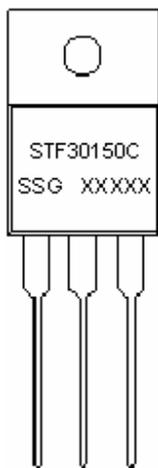


SYMBOL	MIN.	TYP.	MAX.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
b3	1.20	1.30	1.45
b4	1.60	1.70	1.85
c	0.55	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e		2.55	
e1		5.10	
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
ΦP1(上□)	3.30	3.50	3.70
ΦP2(下□)	2.99	3.19	3.39
Q	2.50	2.70	2.90
Θ1		5°	
Θ2		4°	
Θ3		10°	
Θ4		5°	
Θ5		5°	

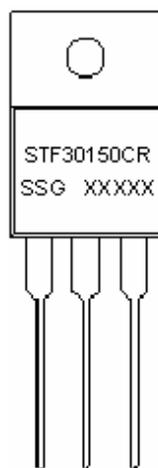
### ITO-220AB



**Marking Diagram:**



**STF30150C**



**STF30150CR**

Where XXXXX is YYWWL

- S = Device Type
- T = Ultralow VF
- F = Package type
- 30 = Forward Current (30A)
- 150 = Reverse Voltage (150V)
- C(R) = Configuration
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL: 94V-0

**Ordering Information:**

Device	Package	Shipping
STF30150C(R)	ITO-220AB (Pb-Free)	50pcs / tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

**Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	$V_{RWM}$	-	150	V
Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C = 100^\circ\text{C}$ rectangular wave form	30	A
Peak One Cycle Non-Repetitive Surge Current (per leg)	$I_{FSM}$	8.3 ms, half Sine pulse	200	A



**Electrical Characteristics:**

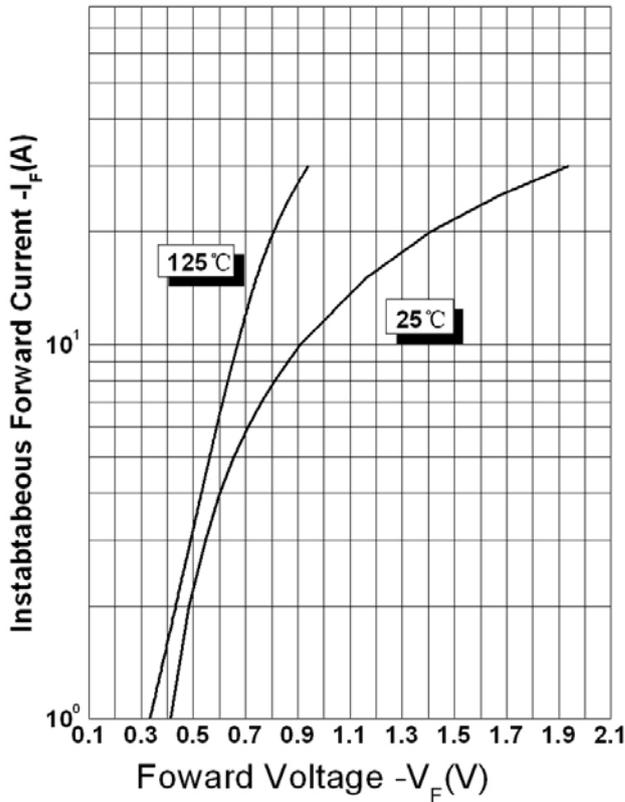
Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop (per leg)*	V <sub>F1</sub>	@ 5A, Pulse, T <sub>J</sub> = 25 °C	0.66	-	V
		@ 7.5A, Pulse, T <sub>J</sub> = 25 °C	0.79	-	
@ 15A, Pulse, T <sub>J</sub> = 25 °C		1.16	1.36		
	V <sub>F2</sub>	@ 5A, Pulse, T <sub>J</sub> = 125 °C	0.56	-	V
		@ 7.5A, Pulse, T <sub>J</sub> = 125 °C	0.62	-	
		@ 15A, Pulse, T <sub>J</sub> = 125 °C	0.74	0.79	
Reverse Current (per leg)	I <sub>R1</sub>	@V <sub>R</sub> = rated V <sub>R</sub> T <sub>J</sub> = 25 °C	0.006	0.2	mA
Reverse Current (per leg) *	I <sub>R2</sub>	@V <sub>R</sub> = rated V <sub>R</sub> T <sub>J</sub> = 125 °C	2.6	20	mA
Junction Capacitance (per leg)	C <sub>T</sub>	@V <sub>R</sub> = 5V, T <sub>C</sub> = 25 °C f <sub>SIG</sub> = 1MHz	670	-	pF
RSM Isolation Voltage (t = 1.0 second, R. H. <=30%, T <sub>A</sub> = 25 °C)	V <sub>ISO</sub>	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.	-	4500	V
		Clip mounting, the epoxy body is inside the heatsink.	-	3500	
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

\* Pulse Width < 300µs, Duty Cycle <2%

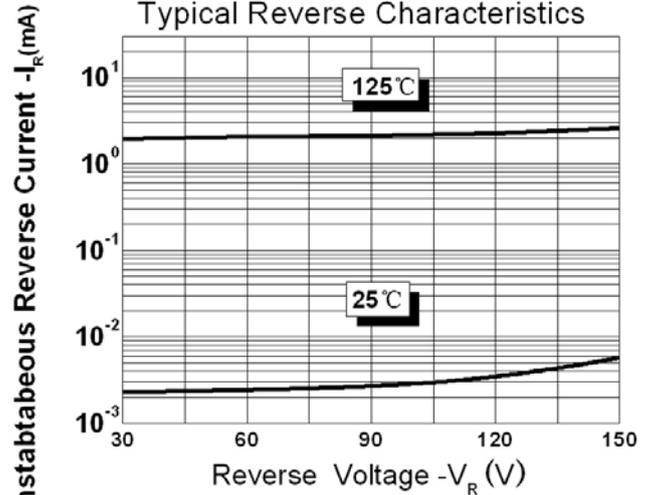
**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T <sub>J</sub>	-	-55 to +150	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +150	°C
Maximum Thermal Resistance Junction to Case (per leg)	R <sub>θJC</sub>	DC operation	4.5	°C/W
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

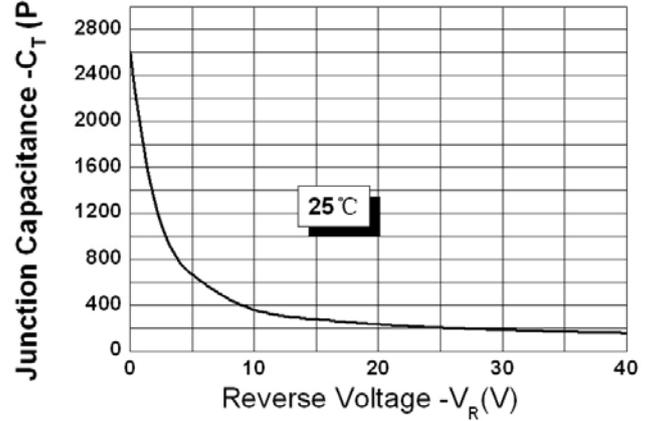
**Figure 1**  
Typical Forward Characteristics



**Figure 2**  
Typical Reverse Characteristics



**Figure 3**  
Typical Junction Capacitance





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